

PRODUCT DATA SHEET

TACFlux® 026

Introduction

TACFlux® 026 is a no-clean and halide-free flux designed especially for flip-chip and CSP (chip-scale package) attachment. It can be also used for 3D packages (POP). **TACFlux® 026** is designed to accommodate a wide range of reflow temperatures, and is suitable for all SnPb, Pb-free, and high-Pb processes.

Features

- Excellent wetting
- Wide reflow temperature range
- No-clean
- Low-residue

Properties

J-STD-004A (IPC-TM-650)	Value
Flux Type Classification	ROLO
Typical Viscosity	330kcps
Typical Acid Number	34
Typical Tack Strength	240g
Reflow Atmosphere	Nitrogen
SIR	Pass
Cleaning	Not needed
Typical Reflow Residual Weight	5%

Application

TACFlux® 026 can be applied by printing, dispensing, pin transfer, or dipping.

Cleaning

TACFlux® 026 is designed for no-clean applications. If necessary, flux residues can be removed by using a semi-aqueous system, saponified water, alcohols, or other CFC-free alternatives.

Packaging

TACFlux® 026 is available in 150g SEMCO cartridges, 10 and 30cc syringes, or 100g jars. Other packaging can be provided to meet specific requirements.

Storage and Handling

The shelf life of **TACFlux® 026** is 6 months when stored at 0–30°C.

Flux should be allowed to reach ambient working temperature prior to use. Packaging should be labeled with date and time of opening.

Technical Support

Indium Corporation's internationally experienced engineers provide in-depth technical assistance to our customers. Thoroughly knowledgeable in all facets of Materials Science as it applies to the electronics and semiconductor sectors, Technical Support Engineers provide expert advice in solder properties, alloy compatibility and selection of solder preforms, wire, ribbon, and paste. Indium Corporation's Technical Support Engineers provide rapid response to all technical inquiries.

Safety Data Sheets

The SDS for this product can be found online at <http://www.indium.com/sds>



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All of Indium Corporation's solder paste and preform manufacturing facilities are IATF 16949:2016 certified. Indium Corporation is an ISO 9001:2015 registered company.

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